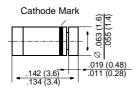
LL4448

Small Signal Diodes

MiniMELE



Dimensions in inches and (millimeters)

FEATURES

- Silicon Epitaxial Planar Diode
- Fast switching diode in MiniMELF case especially suited for automatic insertion.



This diode is also available in other case styles including: the DO-35 case with the type designation 1N4448, the SOD-123 case with the type designation 1N4448W, and the SOT-23 case with the type designation IMBD4448.

MECHANICAL DATA

Case: MiniMELF Glass Case (SOD-80) **Weight:** approx. 0.05 g

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit	
Reverse Voltage	V _R	75	V	
Peak Reverse Voltage	V _{RM}	100	V	
Rectified Current (Average) Half Wave Rectification with Resist. Load at T_{amb} = 25 °C and f \ge 50 Hz	IO	150 ¹⁾	mA	
Surge Forward Current at t < 1 s and $T_j = 25 \text{ °C}$	I _{FSM}	500	mA	
Power Dissipation at T _{amb} = 25 °C	P _{tot}	500 ¹⁾	mW	
Junction Temperature	Tj	175	°C	
Storage Temperature Range	T _S	-65 to +175	°C	

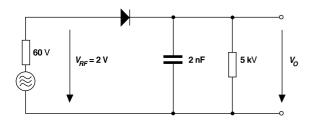


LL4448

ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Тур.	Max.	Unit	
Forward Voltage at $I_F = 5 \text{ mA}$ at $I_F = 100 \text{ mA}$	V _F V _F	0.62 -		0.72 1	V V	
Leakage Current at $V_R = 20 V$ at $V_R = 75 V$ at $V_R = 20 V$, $T_j = 150 °C$	l _R I _R I _R	_ _ _		25 5 50	nA μA μA	
Capacitance at $V_F = V_R = 0$	C _{tot}	_	-	4	pF	
Reverse Recovery Time from I _F = 10 mA to I _R = 1 mA, V _R = 6 V, R _L = 100 Ω	t _{rr}	_	-	4	ns	
Thermal Resistance Junction to Ambient Air	R _{thJA}	-	-	0.351)	K/mW	
Rectification Efficiency at f = 100 MHz, V_{RF} = 2 V	ην	0.45	_	-	-	
¹⁾ Valid provided that electrodes are kept at ambient temperature.						

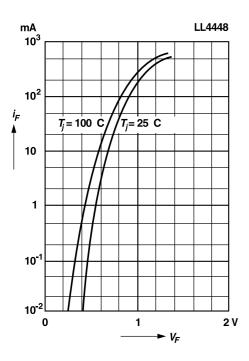


Rectification Efficiency Measurement Circuit

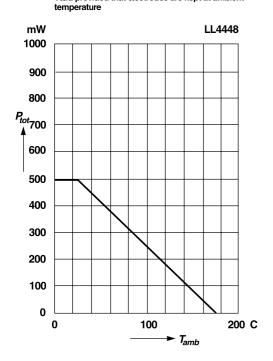


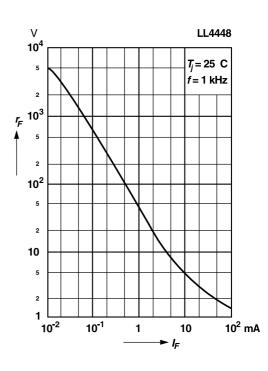
RATINGS AND CHARACTERISTIC CURVES LL4448

Forward characteristics



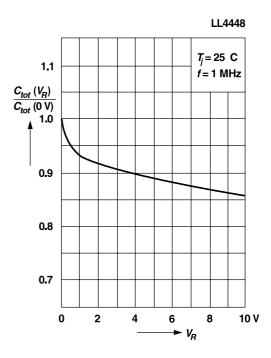
Admissible power dissipation versus ambient temperature Valid provided that electrodes are kept at ambient





Dynamic forward resistance versus forward current

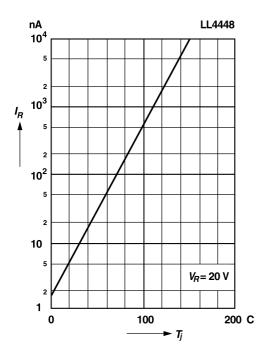
Relative capacitance versus reverse voltage



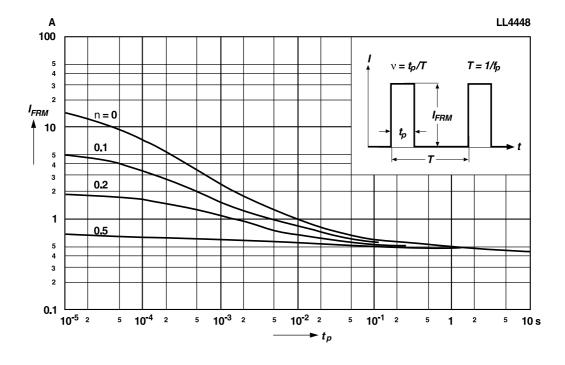
GENERAL SEMICONDUCTOR®

RATINGS AND CHARACTERISTIC CURVES LL4448

Leakage current versus junction temperature



Admissible repetitive peak forward current versus pulse duration Valid provided that electrodes are kept at ambient temperature



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